

FORMING A CHIP PACKAGE
HAVING A NO-FLOW UNDERFILL

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ABSTRACT OF THE DISCLOSURE

10 A method of forming an underfilled chip package is
provided. No-flow underfill material is deposited over a
surface of a package substrate to form an underfill
region. A die having a plurality of solder bumps is
placed at an angle relative to the package substrate such
that solder bumps adjacent a first side of the die
contact the surface of the package substrate within the
underfill region while solder bumps adjacent a second
15 side of the die are generally located at a distance away
from the surface of the package substrate. The second
side of the die is moved toward the surface of the
package substrate until the solder bumps adjacent the
second side of the die contact the surface such that the
20 underfill material is forced into the area between the
plurality of bumps.